## SN74ACT7804 $512 \times 18$ STROBED FIRST-IN, FIRST-OUT MEMORY

SCAS204C - APRIL 1992 - REVISED APRIL 1998

<ul> <li>Member of the Texas Instruments Widebus™ Family</li> </ul>	DL PACK (TOP VIE	AGE EW)
<ul> <li>Load Clock and Unload Clock Can Be Asynchronous or Coincident</li> </ul>		56 ] OE
• 512 Words by 18 Bits		
Low-Power Advanced CMOS Technology	D15 1 4	53 Q15
<ul> <li>Full. Empty. and Half-Full Flags</li> </ul>	D14 🛛 5	52 GND
<ul> <li>Programmable Almost-Full/Almost-Fmpty</li> </ul>	D13 🛛 6	51 🛛 Q14
Flag	D12 🛛 7	50 V <sub>CC</sub>
<ul> <li>East Access Times of 15 ns With a 50-nF</li> </ul>	D11 🛽 8	49 🛛 Q13
Load and All Data Outputs Switching	D10 9	48 Q12
Simultaneously	V <sub>CC</sub> 10	47 Q11
<ul> <li>Data Rates up to 50 MHz</li> </ul>		46 U Q10
3-State Outputs		
Din to Din Compatible With SNZ44 CT700C		
<ul> <li>PIn-to-PIn Compatible with SN/4AC1/806</li> <li>and SN74ACT7814</li> </ul>		
Deckaged in Christ Small Outline 200 mil	D5 1 16	41 06
Packaged in Shrink Sinali-Outline 300-Inil     Package Using 25-mil Conter-to-Conter	D4 17	40 Q5
Snacing	D3 🛛 18	39 0 V <sub>CC</sub>
optioning	D2 🛿 19	38 🛛 Q4
description	D1 🛿 20	37 🛛 Q3
	D0 🛛 21	36 🛛 Q2
A FIFO memory is a storage device that allows	HF [] 22	35 🛛 GND
data to be written into and read from its array at	PEN 23	34 🛛 Q1
Independent data rates. The SN74AC17804 IS a 512-word by 18-bit EIEO for high speed and fast	AF/AE 24	33 Q0
access times. It processes data at rates up to		32 UNCK
50 MHz and access times of 15 ns in a bit-parallel		
50 IVIHZ and access times of 15 ns in a bit-parallel		

NC - No internal connection

30 🛛 NC

empty, UNCK signals have no effect. Status of the FIFO memory is monitored by the full (FULL), empty (EMPTY), half-full (HF), and almost-full/almost-empty (AF/AE) flags. The FULL output is low when the memory is full and high when the memory is not full. The EMPTY output is low when the memory is empty and high when it is not empty. The HF output is high when the FIFO contains 256 or more words. The AF/AE status flag is a programmable flag. The first one or two low-to-high transitions of LDCK after reset are used to program the almost-empty offset value (X) and the almost-full offset value (Y) if program enable (PEN) is low. The AF/AE flag is high when the FIFO contains X or fewer words or (512 - Y) or more words. The AF/AE flag is low when the FIFO contains between (X + 1) and (511 - Y) words.



format.

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Data is written into memory on a low-to-high

transition at the load-clock (LDCK) input and is read out on a low-to-high transition at the unload-clock (UNCK) input. The memory is full when the number of words clocked in exceeds the number of words clocked out by 512. When the memory is full, LDCK signals have no effect on the data residing in memory. When the memory is

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# $\begin{array}{l} \text{SN74ACT7804} \\ \text{512} \times \text{18 STROBED FIRST-IN, FIRST-OUT MEMORY} \end{array}$

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#### description (continued)

A low level on the reset (RESET) input resets the internal stack pointers and sets FULL high, AF/AE high, HF low, and EMPTY low. The Q outputs are not reset to any specific logic level. The FIFO must be reset upon power up.

The first word loaded into empty memory causes  $\overline{\text{EMPTY}}$  to go high and the data to appear on the Q outputs. It is important to note that the first word does not have to be unloaded. The data outputs are noninverting with respect to the data inputs and are in the high-impedance state when the output-enable ( $\overline{\text{OE}}$ ) input is high.

The SN74ACT7804 is characterized for operation from 0°C to 70°C.

#### logic symbol<sup>†</sup>



<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



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### **Terminal Functions**

TEI	RMINAL	1/0	DESCRIPTION
NAME	NO.	1/0	DESCRIPTION
AF/AE	24	0	Almost-full/almost-empty flag. Depth-offset values can be programmed for AF/AE, or the default value of 64 can be used for both the almost-empty offset (X) and the almost-full offset (Y). AF/AE is high when memory contains X or fewer words or $(512 - Y)$ or more words. AF/AE is high after reset.
D0–D17	2–9, 11–12, 14–21	Ι	18-bit data input port
EMPTY	29	0	Empty flag. EMPTY is low when the FIFO is empty. A FIFO reset also causes EMPTY to go low.
FULL	28	0	Full flag. FULL is low when the FIFO is full. A FIFO reset causes FULL to go high.
HF	22	0	Half-full flag. HF is high when the FIFO memory contains 256 or more words. HF is low after reset.
LDCK	25	Ι	Load clock. Data is written to the FIFO on the rising edge of LDCK when FULL is high.
OE	56	Ι	Output enable. When $\overline{OE}$ is high, the data outputs are in the high-impedance state.
PEN	23	Ι	Program enable. After reset and before the first word is written to the FIFO, the binary value on D0–D7 is latched as an AF/AE offset value when PEN is low and LDCK is high.
Q0–Q17	33–34, 36–38, 40–43, 45–49, 51, 53–55	0	18-bit data output port
RESET	1	I	Reset. A low level on RESET resets the FIFO and drives AF/AE and FULL high and HF and EMPTY low.
UNCK	32	I	Unload clock. Data is read from the FIFO on the rising edge of UNCK when EMPTY is high.



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#### offset values for AF/AE

The AF/AE flag has two programmable limits: the almost-empty offset value (X) and the almost-full offset value (Y). They can be programmed after the FIFO is reset and before the first word is written to memory. The AF/AE flag is high when the FIFO contains X or fewer words or (512 - Y) or more words.

To program the offset values,  $\overline{PEN}$  can be brought low after reset only when LDCK is low. On the following low-to-high transition of LDCK, the binary value on D0–D7 is stored as the almost-empty offset value (X) and the almost-full offset value (Y). Holding  $\overline{PEN}$  low for another low-to-high transition of LDCK reprograms Y to the binary value on D0–D7 at the time of the second LDCK low-to-high transition. Writes to the FIFO memory are disabled while the offsets are programmed. A maximum value of 255 can be programmed for either X or Y (see Figure 1). To use the default values of X = Y = 64,  $\overline{PEN}$  must be held high.



Figure 1. Programming X and Y Separately







the Default Value of X and Y

Figure 2. Write, Read, and Flag Timing Reference

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### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub>	0.5 V	/ to 7 V
Input voltage range, V <sub>I</sub>	0.5 V	/ to 7 V
Voltage range applied to a disabled 3-state output	. –0.5 V te	o 5.5 V
Package thermal impedance, θ <sub>JA</sub> (see Note 1)	7	′4°C/W
Storage temperature range, T <sub>stg</sub>	–65°C to	150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51.

#### recommended operating conditions

			'ACT78	304-20	'ACT78	304-25	'ACT78	304-40	LINIT
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage		4.5	5.5	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2		2		2		V
VIL	Low-level input voltage			0.8		0.8		0.8	V
ЮН	High-level output current	Q outputs, flags		-8		-8		-8	mA
IOL Low-level output current		Q outputs		16		16		16	<b>m</b> (
	Low-level output current	Flags		8		8		8	ША
TA	Operating free-air temperature		0	70	0	70	0	70	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PA	RAMETER		TEST CONDITIONS	MIN	MIN TYP <sup>‡</sup> MAX			
VOH	-	V <sub>CC</sub> = 4.5 V,	I <sub>OH</sub> = -8 mA	2.4			V	
Vei	Flags	V <sub>CC</sub> = 4.5 V,	I <sub>OL</sub> = 8 mA			0.5	V	
VOL	Q outputs			0.5	v			
Ц		V <sub>CC</sub> = 5.5 V,	$V_I = V_{CC} \text{ or } 0$			±5	μΑ	
I <sub>OZ</sub>		V <sub>CC</sub> = 5.5 V,	VO = NCC or 0			±5	μΑ	
ICC		V <sub>CC</sub> = 5.5 V,	$V_{I} = V_{CC} - 0.2 V \text{ or } 0$			400	μΑ	
∆ICC§		V <sub>CC</sub> = 5.5 V,	One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND			1	mA	
Ci		$V_{I} = 0,$	f = 1 MHz		4		pF	
Co		$V_{O} = 0,$	f = 1 MHz		8		pF	

<sup>‡</sup> All typical values are at  $V_{CC} = 5 V$ ,  $T_A = 25^{\circ}C$ .

\$ This is the supply current for each input that is at one of the specified TTL voltage levels rather 0 V or V<sub>CC</sub>.



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### timing requirements over recommended operating conditions (see Figures 1 through 3)

			'ACT78	304-20	'ACT78	804-25	'ACT78	804-40		
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT	
fclock	Clock frequency			50		40		25	MHz	
		LDCK high or low	7		8		12			
t <sub>w</sub> I	Pulse duration	UNCK high or low	7		8		12			
		PEN low	7		8		12		ns	
		RESET low	10		10		12			
		D0–D17 before LDCK↑	5		5		5			
t <sub>su</sub>	Setup time	PEN before LDCK↑	5		5		5		ns	
		LDCK inactive before RESET high	5		6		6			
		D0–D17 after LDCK↑	0		0		0			
L	Hold time	LDCK inactive after RESET high 5		6		6				
th Ho		PEN low after LDCK↑	3		3		3		115	
		PEN high after LDCK↓	0		0		0			

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 3)

DADAMETED	FROM	то	'A	CT7804-:	20	'ACT78	804-25	'ACT78			
PARAMETER	(INPUT)	(OUTPUT)	MIN	түр†	MAX	MIN	MAX	MIN	MAX	UNIT	
f <sub>max</sub>	LDCK or UNCK		50			40		25		MHz	
<b>•</b> .	LDCK↑	Amy O	9		20	9	22	9	24	20	
۲pd	UNCK↑	Any Q	6	11.5	15	6	18	6	20	115	
t <sub>pd</sub> ‡	UNCK↑	Any Q		10.5						ns	
<sup>t</sup> PLH	LDCK↑	EMPTY	6		15	6	17	6	19	ns	
	UNCK↑		6		15	6	17	6	19		
<sup>t</sup> PHL	RESET low	EMPTY	4		16	4	18	4	20	ns	
	LDCK↑	FULL	6		15	6	17	6	19		
4	UNCK↑	<b>C</b> 1.11.1	6		15	6	17	6	19		
PLH	RESET low	FULL	4		18	4	20	4	22	IIS	
÷.	LDCK↑		7		18	7	20	7	22	50	
чрd	UNCK↑	AF/AE	7		18	7	20	7	22	2 ns	
t=	RESET low	AF/AE	2		10	2	12	2	14	20	
PLH	LDCK↑	HF	5		18	5	20	5	22	ns	
to u	UNCK↑	ЦС	7		18	7	20	7	22	nc	
PHL	RESET low		3		12	3	14	3	16	115	
ten	OE	Any Q	2		9	2	10	2	11	ns	
tdis	OE	Any Q	2		10	2	11	2	12	ns	

<sup>†</sup> All typical values are at  $V_{CC}$  = 5 V,  $T_A$  = 25°C. <sup>‡</sup> This parameter is measured at  $C_L$  = 30 pF (see Figure 4).

### operating characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = $25^{\circ}$ C

	PARAMETER	TEST CO	TYP	UNIT		
C <sub>pd</sub>	Power dissipation capacitance per FIFO channel	Outputs enabled	C <sub>L</sub> = 50 pF,	f = 5 MHz	53	pF



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NOTE A: C<sub>L</sub> includes probe and jig capacitance.





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### **TYPICAL CHARACTERISTICS**



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**APPLICATION INFORMATION** 





#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
1M7804-20DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
1M7804-20DLRG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT7804-20DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT7804-20DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT7804-25DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT7804-40DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT7804-40DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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### TAPE AND REEL INFORMATION





## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*	All dimensions are nominal													
	Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant	
I	SN74ACT7804-20DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1	
ſ	SN74ACT7804-40DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1	



# PACKAGE MATERIALS INFORMATION

9-Aug-2008



\*All dimensions are nominal

Device	Package Type	pe Package Drawing		SPQ	Length (mm)	Width (mm)	Height (mm)	
SN74ACT7804-20DLR	SSOP	DL	56	1000	346.0	346.0	49.0	
SN74ACT7804-40DLR	SSOP	DL	56	1000	346.0	346.0	49.0	